Abstract

The invention relates to a carrier body (1, 2) for electrical or electronic component elements (6a, 6b, 6c, 6d) or circuits, the carrier body (1, 2) being electrically nonconductive or virtually nonconductive.

In order to simplify the carrier body (1) whilst at the same time providing extremely improved heat dissipation, the invention proposes that the carrier body (1, 2) is provided integrally with heat-dissipating or heat-supplying cooling elements (7).

(Figure 2)